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Field device integration (FDI) - Part 1: Overview

Táto norma obsahuje anglickú verziu európskej normy.  
This standard includes the English version of the European Standard.

Táto norma bola oznámená vo Vestníku ÚNMS SR č. 11/15

Obsahuje: EN 62769-1:2015, IEC 62769-1:2015

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Úrad pre normalizáciu, metrológiu a skúšobníctvo SR, 2015  
Podľa zákona č. 264/1999 Z. z. v znení neskorších predpisov sa môžu slovenské technické normy  
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EUROPEAN STANDARD

**EN 62769-1**

NORME EUROPÉENNE

EUROPÄISCHE NORM

June 2015

ICS 25.040.40; 35.100

## English Version

**Field device integration (FDI) - Part 1: Overview  
(IEC 62769-1:2015)**

Intégration des appareils de terrain (FDI) - Partie 1: Vue  
d'ensemble  
(IEC 62769-1:2015)

Feldgeräteintegration (FDI) - Teil 1: Überblick  
(IEC 62769-1:2015)

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**European foreword**

The text of document 65E/337/CDV, future edition 1 of IEC 62769-1, prepared by SC 65E "Devices and integration in enterprise systems" of IEC/TC 65 "Industrial-process measurement, control and automation" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 62769-1:2015.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2016-03-16
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2018-06-16

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In the official version, for Bibliography, the following notes have to be added for the standards indicated:

IEC 61804-3	NOTE	Harmonized as EN 61804-3.
IEC/TR 61804-4	NOTE	Harmonized as CLC/TR 61804-4.
IEC 62769-4	NOTE	Harmonized as EN 62769-4.
IEC 62769-5	NOTE	Harmonized as EN 62769-5.
IEC 62769-6	NOTE	Harmonized as EN 62769-6.

## Annex ZA (normative)

### **Normative references to international publications with their corresponding European publications**

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 When an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: [www.cenelec.eu](http://www.cenelec.eu).

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
	series			series
IEC 61804	series	Function Blocks (FB) for process control	EN 61804	
IEC 62453	series	Field device tool (FDT) interface specification	EN 62453	series
IEC 62541-3	-	OPC unified architecture - Part 3: Address Space Model	EN 62541-3	-
IEC 62541-4	-	OPC Unified Architecture - Part 4: Services	EN 62541-4	-
IEC 62541-5	-	OPC unified architecture - Part 5: Information Model	EN 62541-5	-
IEC 62541	series	OPC Unified Architecture	EN 62541	series
IEC 62541-100	-	OPC unified architecture - Part 100: Device Interface	EN 62541-100	-
IEC 62769-2	-	Devices and integration in enterprise systems; Field Device Integration - Part 2: FDI Client	-	-
IEC 62769-3	-	Devices and integration in enterprise systems; Field Device Integration - Part 3: FDI Server	-	-
IEC 62769-4	2015	Devices and integration in enterprise systems; Field Device Integration - Part 4: FDI Packages	-	-
IEC 62769-5	-	Devices and integration in enterprise systems; Field Device Integration - Part 5: FDI Information Model	-	-
IEC 62769-6	2015	Devices and integration in enterprise systems; Field Device Integration - Part 6: Technology Mapping	-	-
IEC 62769-7	2015	Devices and integration in enterprise systems; Field Device Integration - Part 7: Communication Devices	-	-
IEC/TR 62541-1	-	OPC unified architecture - Part 1: Overview and concepts	CLC/TR 62541-1	-
ISO/IEC 11578	-	Information technology - Open Systems Interconnection - Remote Procedure Call (RPC)	-	-



# INTERNATIONAL STANDARD

# NORME INTERNATIONALE



**Field device integration (FDI) –  
Part 1: Overview**

**Intégration des appareils de terrain (FDI) –  
Partie 1: Vue d'ensemble**





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# INTERNATIONAL STANDARD

## NORME INTERNATIONALE



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**Field device integration (FDI) –  
Part 1: Overview**

**Intégration des appareils de terrain (FDI) –  
Partie 1: Vue d'ensemble**

INTERNATIONAL  
ELECTROTECHNICAL  
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## FIELD DEVICE INTEGRATION (FDI) –

### Part 1: Overview

#### FOREWORD

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International Standard IEC 62769-1 has been prepared by subcommittee 65E: Devices and integration in enterprise systems, of IEC technical committee 65: Industrial-process measurement, control and automation.

The text of this standard is based on the following documents:

CDV	Report on voting
65E/337/CDV	65E/421/RVC

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 62769 series, published under the general title *Field Device Integration (FDI)*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

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## INTRODUCTION

The IEC 62657 series has the general title "Field Device Integration (FDI)" and the following parts:

- Part 1: Overview
- Part 2: FDI Client
- Part 3: FDI Server
- Part 4: FDI Packages
- Part 5: FDI Information Model
- Part 6: FDI Technology Mapping
- Part 7: FDI Communication Devices
- Part 101-1: Profiles – Foundation Fieldbus H1
- Part 101-2: Profiles – Foundation Fieldbus HSE
- Part 103-1: Profiles – PROFIBUS
- Part 103-4: Profiles – PROFINET
- Part 109-1: Profiles – HART and WirelessHART

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- a) method for the supplying and installation of device-specific functionalities, see Patent Family DE10357276;
- b) method and device for accessing a functional module of automation system, see Patent Family EP2182418;
- c) methods and apparatus to reduce memory requirements for process control system software applications, see Patent Family US2013232186;
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## FIELD DEVICE INTEGRATION (FDI) –

### Part 1: Overview

## 1 Scope

This part of IEC 62769 describes the concepts and overview of the Field Device Integration (FDI) specifications. The detailed motivation for the creation of this technology is also described (see 4.1). Reading this document is helpful to understand the other parts of this multi-part standard.

## 2 Normative references

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 61804 (all parts), *Function blocks (FB) for process control and Electronic Device Description Language (EDDL)*

IEC 62453 (all parts), *Field device tool (FDT<sup>®</sup>) interface specification*

IEC 62541 (all parts), *OPC Unified Architecture*

IEC TR 62541-1, *OPC Unified Architecture – Part 1: Overview and concepts*

IEC 62541-3, *OPC Unified Architecture – Part 3: Address Space Model*

IEC 62541-4, *OPC Unified Architecture – Part 4: Services*

IEC 62541-5, *OPC Unified Architecture – Part 5: Information Model*

IEC 62541-100, *OPC Unified Architecture – Part 100: Device Interface*

IEC 62769-2, *Field Device Integration (FDI) – Part 2: FDI Client*

NOTE IEC 62769-2 is technically identical to FDI-2022[4] <sup>1</sup>

IEC 62769-3, *Field Device Integration (FDI) – Part 3: FDI Server*

NOTE IEC 62769-3 is technically identical to FDI-2023. [5]

IEC 62769-4:2015, *Field Device Integration (FDI) – Part 4: FDI Packages*

NOTE IEC 62769-4 is technically identical to FDI-2024. [6]

IEC 62769-5:2015, *Field Device Integration (FDI) – Part 5: FDI Information Model*

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<sup>1</sup> Numbers in square brackets refer to the Bibliography.

NOTE IEC 62769-5 is technically identical to FDI-2025. [7]

IEC 62769-6:2015, *Field Device Integration (FDI) – Part 6: FDI Technology Mapping*

NOTE IEC 62769-6 is technically identical to FDI-2026. [8]

IEC 62769-7, *Field Device Integration (FDI) – Part 7: FDI Communication Devices*

NOTE IEC 62769-7 is technically identical to FDI-2027. [9]

ISO/IEC 11578, *Information technology – Open Systems Interconnection – Remote Procedure Call (RPC)*

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